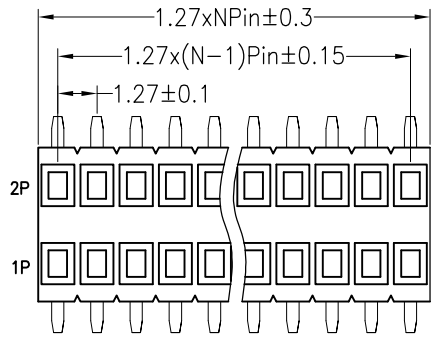
HSF RoHS

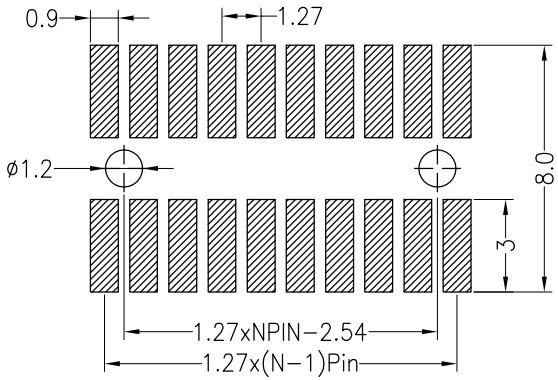
FILE NO :E362810

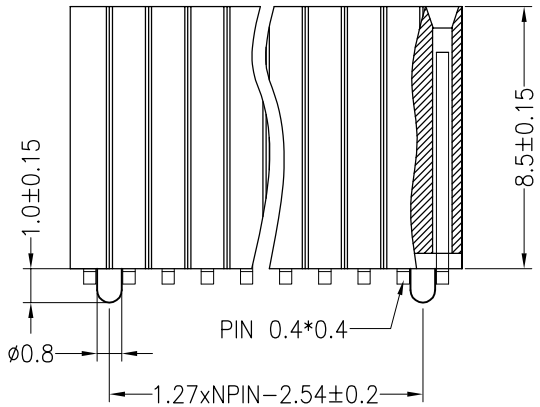
SPECIFICATIONS
Rated Current:1.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:500V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

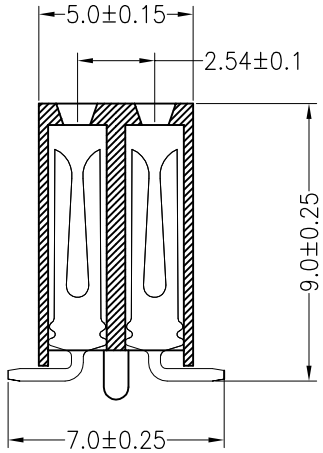
Contact Material:Brass
Contact Plating:Au Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)




Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)




## Ordering Information

2585 02 XX X X XX M Y X 01

| | | | | | |
|---|---|---|---|---|---|
| No.of Pins Per Row 2*50 | Insulator Material Option | Post | Contact Plating | Packing | |
| | C=BK−PA6T | W=With Post | G1: Gold Flash | T=Tube | |
| | D=BK−PA46 | N=W/O Post | G2:1.5U" Gold | P=Tube+Cap | |
| | E=BK−PA9T | | G3:2U" Gold | R=Reel+Cap | |
| | F=BK−LCP | | G4:3U" Gold | M=Reel+Mylar | |
| | | | G5:5U" Gold | | |
| | | | S0:Gold Flash/Tin | | |
| | | | SN:Tin | | |

| REV | DATE | MODIFICATION DESCRIPTION | CHANGE |
|---|---|---|---|
| A0 | 2012.09.11 | NEW DRAWING | |

| OPERATION | |
|---|---|
| X.X | ±0.30 |
| X.XX | ±0.20 |
| X.XXX | ±0.10 |
| Angle | ±3° |
| DIM | TOL |

| | | |
|---|---|---|
| DRAW | Liu Miao | 12.09.11 |
| CHECK | | |
| APPROVE | | |

| | |
|---|---|
| SCALE | FIT |
| UNIT | mm |
| SIZE | A4 |
| SHEET | 1/1 |
| PROJ. | |

WFD CONN 深圳市旺富达电子有限公司
SHEN ZHEN WFD ELECTRONICS CO., LTD

| | |
|---|---|
| PART NO. | 258502XXXXXXMY01 |
| TITLE: | 1.27x2.54PF 2xnPin H8.5 SMT |